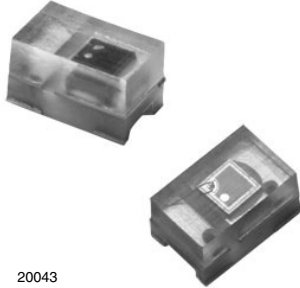


Silicon Phototransistor in 0805 Package



20043

DESCRIPTION

TEMT7000X01 is a high speed silicon NPN epitaxial planar phototransistor in a miniature 0805 package for surface mounting on printed boards. The device is sensitive to visible and near infrared radiation.

FEATURES

- Package type: surface mount
- Package form: 0805
- Dimensions (L x W x H in mm): 2 x 1.25 x 0.85
- AEC-Q101 qualified
- High photo sensitivity
- High radiant sensitivity
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 60^\circ$
- Package matched with IR emitter series VSMB1940X01
- Floor life: 168 h, MSL 3, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Compliant to RoHS directive 2002/95/EC and in accordance to WEEE 2002/96/EC
- Find out more about Vishay's Automotive Grade Product requirements at: www.vishay.com/applications


RoHS
COMPLIANT


APPLICATIONS

- Detector in automotive applications
- Light sensors
- Radiation sensors

PRODUCT SUMMARY

COMPONENT	I_{caE} (μA)	φ (deg)	$\lambda_{0.1}$ (nm)
TEMT7000X01	225 to 675	± 60	470 to 1090

Note

Test condition see table "Basic Characteristics"

ORDERING INFORMATION

ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
TEMT7000X01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	0805

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS

PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Collector emitter voltage		V_{CEO}	20	V
Emitter collector voltage		V_{ECO}	7	V
Collector current		I_C	20	mA
Power power dissipation	$T_{amb} \leq 55^\circ C$	P_V	100	mW
Junction temperature		T_j	100	$^\circ C$
Operating temperature range		T_{amb}	- 40 to + 100	$^\circ C$
Storage temperature range		T_{stg}	- 40 to + 100	$^\circ C$
Soldering temperature	Acc. reflow profile fig. 7	T_{sd}	260	$^\circ C$
Thermal resistance junction/ambient	Acc. J-STD-051	R_{thJA}	270	K/W

Note
 $T_{amb} = 25^\circ C$, unless otherwise specified

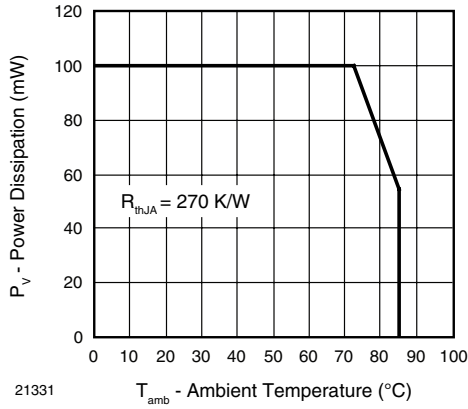


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

BASIC CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Collector emitter breakdown voltage	$I_C = 0.1 \text{ mA}$	V_{CE0}	20			V
Collector dark current	$V_{CE} = 5 \text{ V}, E = 0$	I_{CE0}		1	100	nA
Collector emitter capacitance	$V_{CE} = 0 \text{ V}, f = 1 \text{ MHz}, E = 0$	C_{CE0}		25		pF
Collector light current	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}, V_{CE} = 5 \text{ V}$	I_{CA}	225	450	675	μA
Angle of half sensitivity		ϕ		± 60		deg
Wavelength of peak sensitivity		λ_p		850		nm
Range of spectral bandwidth		$\lambda_{0.1}$		470 to 1090		nm
Collector emitter saturation voltage	$I_C = 0.05 \text{ mA}$	V_{CEsat}			0.4	V

Note

$T_{amb} = 25 \text{ }^\circ\text{C}$, unless otherwise specified

BASIC CHARACTERISTICS

$T_{amb} = 25 \text{ }^\circ\text{C}$, unless otherwise specified

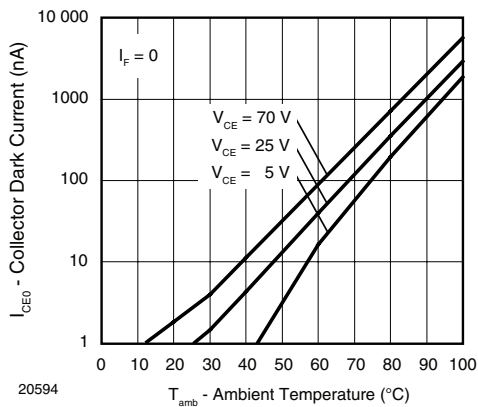


Fig. 2 - Collector Dark Current vs. Ambient Temperature

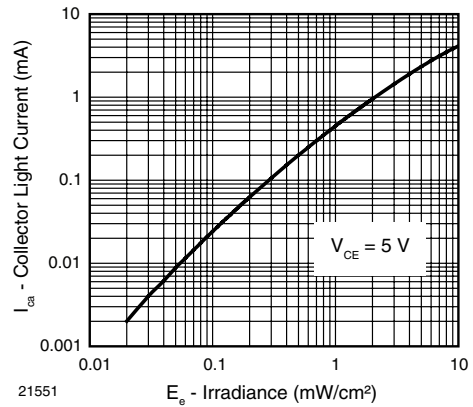


Fig. 3 - Collector Light Current vs. Irradiance

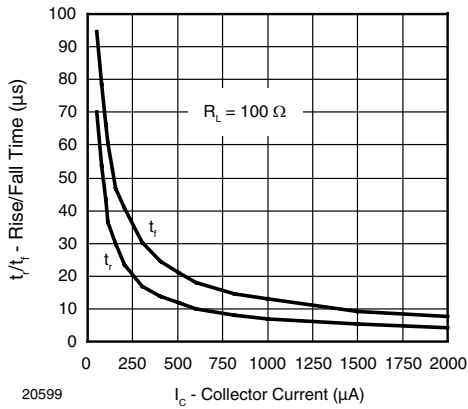


Fig. 4 - Rise/Fall Time vs. Collector Current

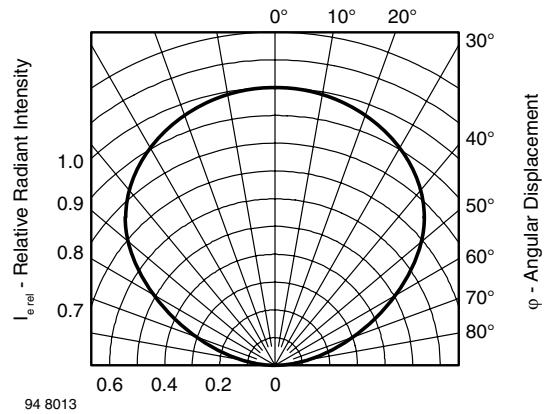


Fig. 6 - Relative Radiant Sensitivity vs. Angular Displacement

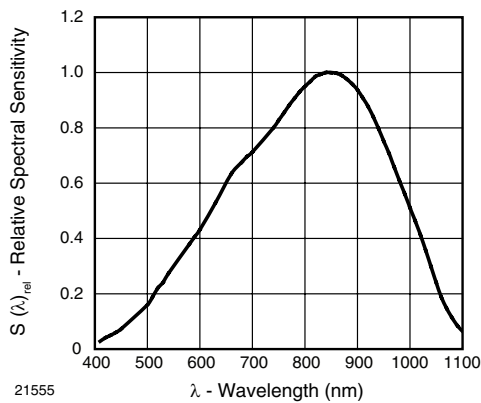


Fig. 5 - Relative Spectral Sensitivity vs. Wavelength

REFLOW SOLDER PROFILE

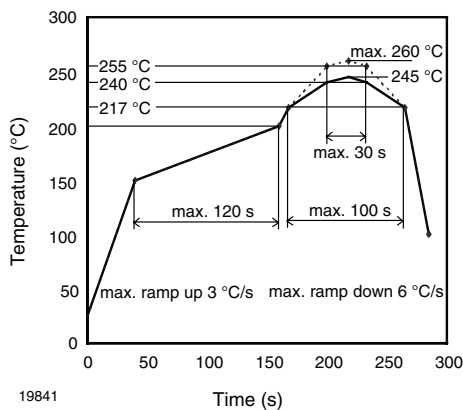


Fig. 7 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 168 h

Conditions: $T_{amb} < 30\text{ }^{\circ}\text{C}$, $\text{RH} < 60\%$

Moisture sensitivity level 3, acc. to J-STD-020.

DRYING

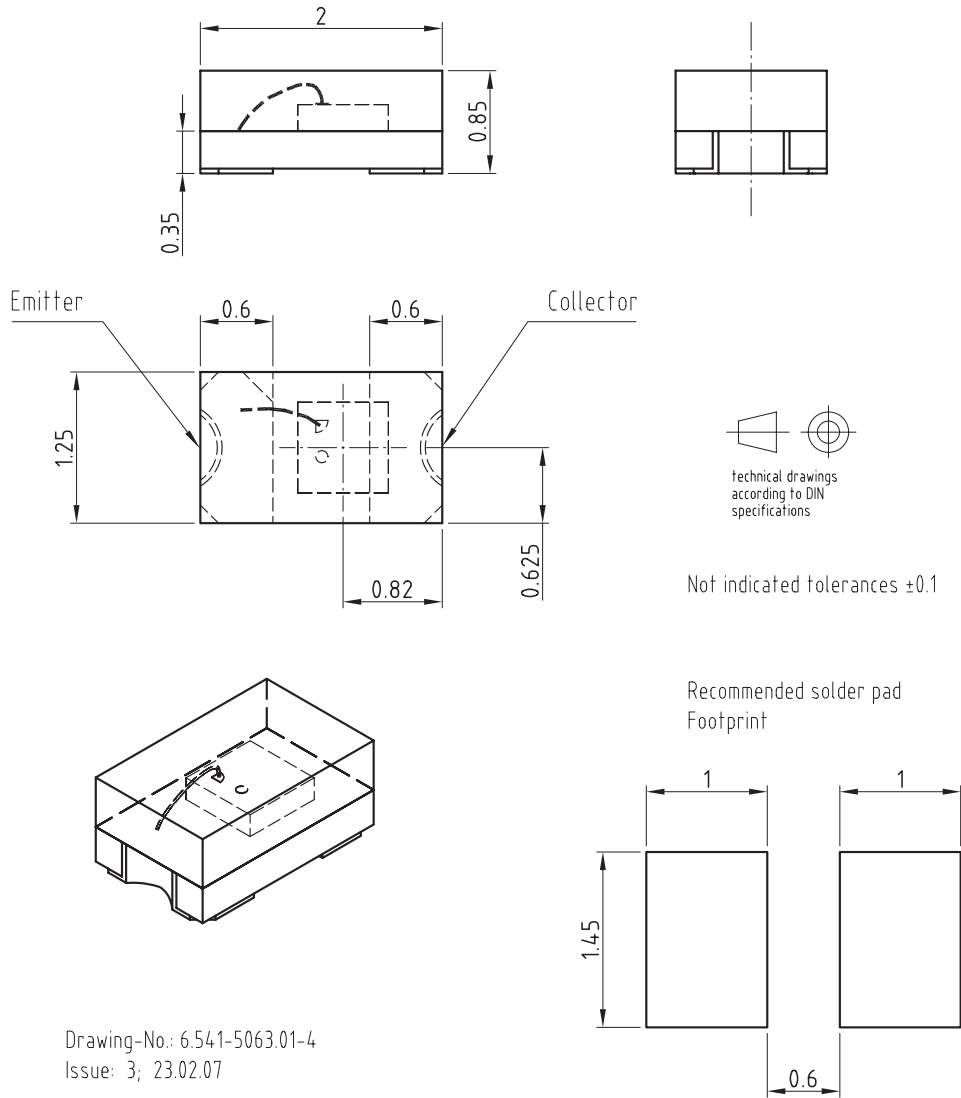
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at $40\text{ }^{\circ}\text{C}$ (+ $5\text{ }^{\circ}\text{C}$), $\text{RH} < 5\%$.

TEMT7000X01

Vishay Semiconductors Silicon Phototransistor in 0805 Package



PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.541-5063.01-4
Issue: 3; 23.02.07

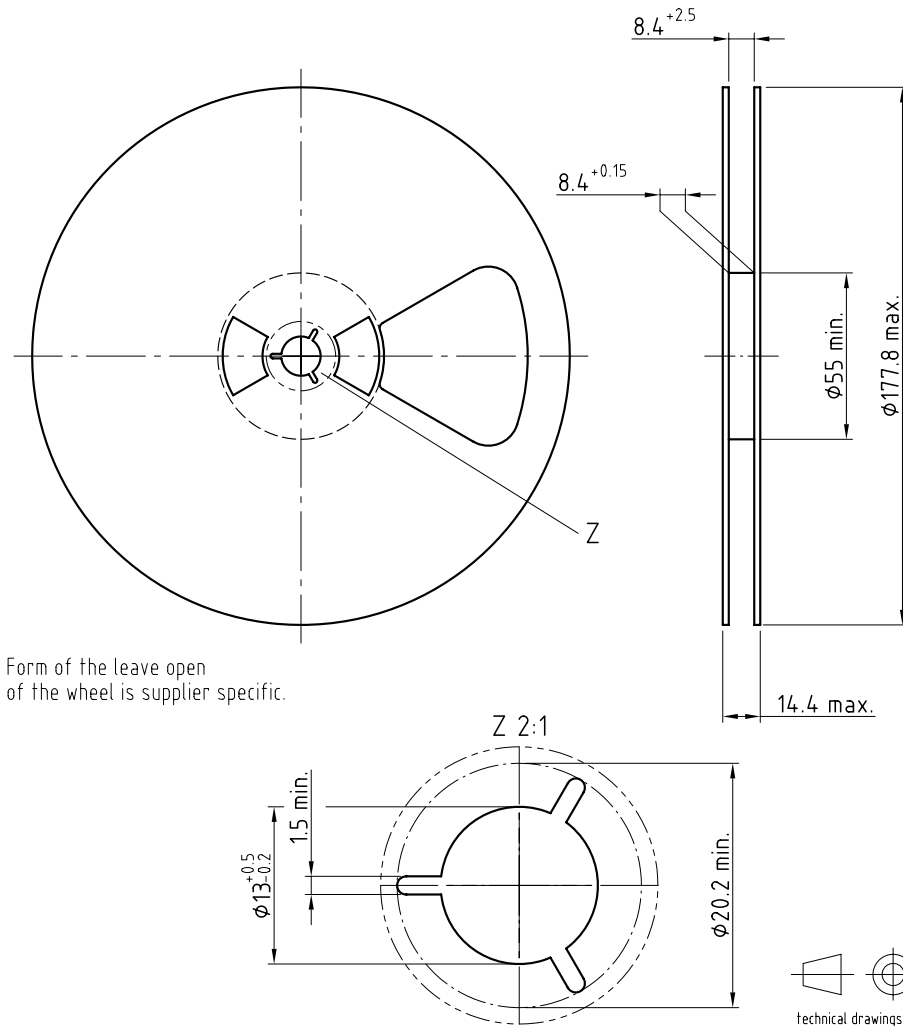
19757

TEMT7000X01

Vishay Semiconductors Silicon Phototransistor in 0805 Package



REEL DIMENSIONS in millimeters



Drawing-No.: 9.800-5096.01-4

Issue: 1; 05.05.08

20875



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